

Declaration For Patent Application

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

INTERCELLULAR ADHESION MOLECULES, AND THEIR BINDING LIGANDS

the specification of which

(check one)

☐ is attached hereto.

☒ was filed on April 27, 1990 as

Application Serial No. 07/515,478

and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number) (Country) (Day/Month/Year Filed)

☐
Yes

☐
No

(Number) (Country) (Day/Month/Year Filed)

☐
Yes

☐
No

(Number) (Country) (Day/Month/Year Filed)

☐
Yes

☐
No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

07/456,647
(Application Serial No.)

Dec. 22, 1989
(Filing Date)

Pending
(Status)
(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Timothy A. Springer		- 6-6-90	
Inventor's signature <i>Timothy A. Springer</i>		Date	
Residence 28 Moradnock Rd. Newton MA			
Citizenship USA			
Post Office Address 28 Moradnock Rd. Newton, MA 02167			
Full name of second joint inventor, if any			
Second Inventor's signature Robert Rothlein		Date	
Residence			
Citizenship			
Post Office Address			

Full name of third Inventor, if any	
<u>Steven D. Marlin</u>	
Third Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	
Full name of fourth Inventor, if any 4-00	
<u>Michael L. Dustin</u>	
Fourth Inventor's signature	Date
<u>Michael L. Dustin</u>	<u>6/8/90</u>
Residence	
<u>8350 Orchard University City (MO) 63132</u>	
Citizenship	
<u>USA</u>	
Post Office Address	
<u>Same as res.</u>	
Full name of fifth Inventor, if any	
Fifth Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	
Full name of sixth Inventor, if any	
Second Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	

(Supply similar information and signature for subsequent joint inventors, if any.)

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07/456,647
(Application Serial No.)

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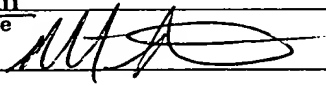
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Full name of sole or first inventor Timothy A. Springer	
Inventor's signature 	Date
Residence 	
Citizenship 	
Post Office Address 	
Full name of second joint inventor, if any 2-00	
Robert Rothlein	
Second Inventor's signature 	Date June 8, 1990
Residence 32 Tamanny Tr., Danbury, CT 06811	
Citizenship U.S.	
Post Office Address same	

Full name of third Inventor, if any 3-00 Steven D. Marlin	
Third Inventor's signature <i>[Signature]</i>	Date June 8, 1990
Residence 18 TERRE HAUTE RD, DANBURY, CT 06810, USA	
Citizenship U.S.A	
Post Office Address SAME.	
Full name of fourth Inventor, if any Michael L. Dustin	
Fourth Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	
Full name of fifth Inventor, if any	
Fifth Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	
Full name of sixth Inventor, if any	
Second Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	

(Supply similar information and signature for subsequent joint inventors, if any.)